

TAICENN TPC-DCT/DRT T – Flagship Industrial Modular Touch Panel PCs with Intel 11th Gen. Tiger Lake UP3 processors



TAICENN has launched our newest modular industrial touchscreen Panel PC series, the TPC-DCT/DRT T series. The Panel PC series is a ruggedized, cableless & flat designed with full dimensions (from 15.0”to 21.5”) that’s to provide the most stable and reliable product solution for industrial HMI applications. As always, this new series HMI Panel PCs shares the same cut-out dimension on both Pcap. touch (TPC-DCT T series) and high temp. 5-wires resistive touch (TPC-DRT T series). It is modular designed and manufactured by the standard Pcap. and resistive touch display modules and newer computer modules.

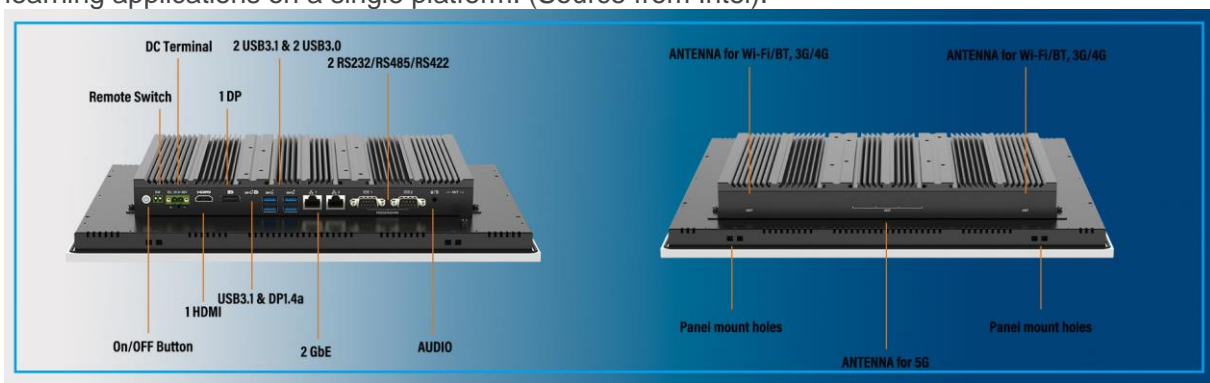
The newest released Tiger Lake Panel PC system is powered by Intel’s 11th Gen. Intel Tiger Lake UP3 SoC based platform (Core i3-1115G4, Core i5-1135G7, Core i7-1165G7) processors for power-efficiency performance. The integrated Intel Iris Xe Graphics built with innovative GPU architecture are able to optimize image and video handling capabilities.

The new TPC-DCT/DRT T series industrial HMI embedded system support TPM2.0 (PTT2.0) and Windows 11 Operating systems, and exceptional 3 high speed expansion modules slots: 1* M.2 3042/3052 B-key slot with built-in SIM card slot to support 4G/5G/Wi-Fi6 cellular network; 1* M.2 2242 E-key to support Wi-Fi/BT wireless network and 1* Mini-PCIe slot for more requested modules or wireless expansions. It’s an ideal solution for various of industrial projects, including

Machine-to-Machine (M2M), smart building automation, industrial automation, Industrial Internet of Things (IIoT), smart manufacturing, industry 4.0, commercial automation

Outstanding performance - Intel's newest 11th Gen. Tiger Lake UP3

TPC-DCT/DRT T series industrial HMI Panel PCs adopts Intel's newest 11th Gen. Tiger Lake UP3 chips. The 11th Gen. Intel® Core™ processors deliver a balance of performance and responsiveness in a low-power platform built on our third-generation 10nm process technology. Engineered to deliver for IoT markets, these processors can support low-latency and time-sensitive applications, and have the power to run multiple workloads including AI and deep learning applications on a single platform. (Source from Intel).



Rich IOs and expansions – More expansion to meet more industrial needs

The rugged touch Panel PC is designed with rich IO interfaces, 2* GbE, 2* USB3.0 (USB3.2 Gen1 x1 5Gbps), 2* USB3.1 (USB3.2 Gen2 x1 10Gbps), 2* RS232/RS422/RS485 (BIOS configured), 1* HDMI, 1* DP, Audio, 1* Optional USB type C (USB3.2 Gen2 x1 10Gbps & DP1.4a), can meet different interface requirements and help information transmission more smoothly. It is designed with 3 high speed expansion slots (1* M.2 3042/3052 Key-B, 1* M.2 2242 Key-E and 1* Mini-PCIe), can optional support 3G/4G, 5G, Wi-Fi6, Wi-Fi/BT wireless functions. Also, TPC-DCT/DRT T series provides more powerful expansion possibilities, and offer flexible and fast expansions for industrial field applications to improve product performance.

Main features:

- High strength aluminum alloy, anodized and painting treatment;
- Available: 15.0" XGA, 15.6" WXGA, 15.6" FHD, 17.0" SXGA, 18.5" WXGA, 18.5" FHD, 19.0" SXGA and 21.5" FHD;

- On-board Intel 11th Gen. Tiger Lake UP3 Core i3-1115G4, Core i5-1135G7, Core i7-1165G7 processors;
- Intel PTT TPM2.0, support to install Win11 OS;
- Support both Pcap. Touch and 5-wires resistive touch, EETI controller;
- 2* DDR4 memory, single slot, max. up to 64GB,
- 1* M.2 2280(PCIe x4 NVMe) SSD, and 1* 2.5" SATA SSD;
- Wide voltage DC 9~36V input, with over-voltage, over-current and polarity protection;
- 3 expansion slots, optional 3G/4G, 5G, Wi-Fi6, WIFI/BT support;
- 2 GLAN, 2 USB3.0, 2 USB3.1, 2 COM, 1 HDMI, 1 DP, Audio;
- Panel mount, support VESA 75/100 mounting method;
- Fanless design, Cableless & slim design, front IP65 rated protection.